



Product Change Notification

Change Notification #: 115326 - 00
Change Title: Intel® Server System R2208WT2YSR
PCN 115326-00, Product Design,
Change dimension on PCIe* riser bracket
holes.
Date of Publication: March 06, 2017

Key Characteristics of the Change:
Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material *:	March 21, 2017
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following change on the Intel® Server System R2312WTTYSR.

- The width of the holes in the PCIe* Riser bracket change from 2.4mm to 2.8mm. Please see Image below for details.

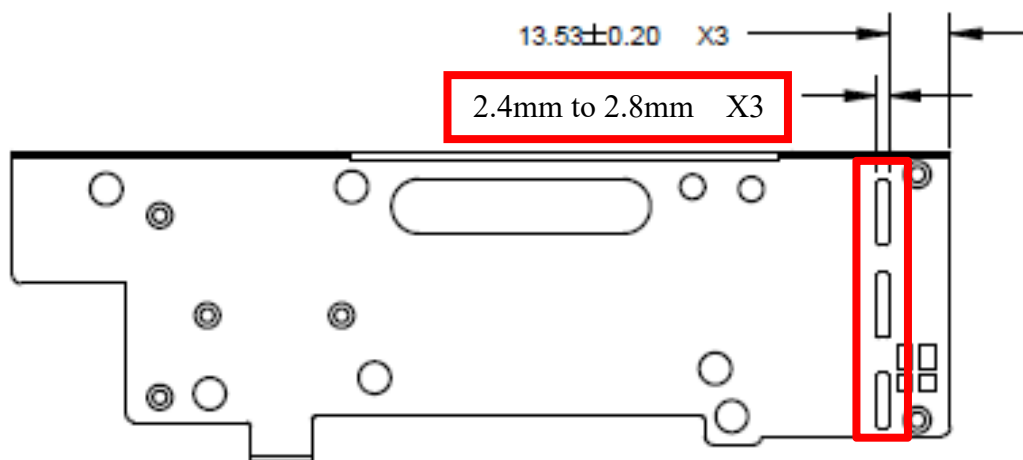


Image 1. PCIe* bracket holes

This change will eliminate any difficulty with customers installing PCIe* cards in riser 2 and riser 3 on opposing PCIe* slots.

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications. For that reason Intel recommends that the customer perform a standard level of evaluation.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre-TA#	Post-TA#
R2208WT2YSR	943827	J11485-004	J11485-005

PCN Revision History:

Date of Revision:

March 06, 2017

Revision Number:

00

Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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